

This listing of claims replaces all prior versions of the claims in this Application.

**Listing of the Claims**

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Claims 1-19 (Canceled).

Claim 20. (Previously Presented) A method of manufacturing a device comprising the steps of:  
a) disposing a composition comprising one or more multi-ethylenically unsaturated monomers on a device substrate; b) curing the one or more multi-ethylenically unsaturated monomers to form a cross-linked polymeric sacrificial material layer on the device substrate; c) disposing an overlayer material on the sacrificial material layer; and then d) removing the sacrificial material layer to form an air gap.

Claim 21. (Previously Presented) The method of claim 20 wherein the composition further comprises a polymer.

Claim 22. (Previously Presented) The method of claim 21 wherein the polymer is a cross-linked polymer particle.

Claim 23. (Previously Presented) The method of claim 20 wherein the one or more multi-ethylenically unsaturated monomers are (meth)acrylate monomers.

Claim 24. (Previously Presented) The method of claim 20 wherein the overlayer material is an organic polysilica material.

Claim 25. (Previously Presented) The method of claim 20 wherein the sacrificial material layer is photoimageable.

Claim 26. (Previously Presented) The method of claim 20 further comprising the steps of i) patterning the overlayer material and the sacrificial material layer to form features; and ii) depositing a metal into the features, wherein steps i) and ii) are performed after step c) and before step d).